

TITLE OF THE INVENTION: SEMICONDUCTOR PACKAGE AND METHOD FOR MAKING THE SAME

Abstract

A semiconductor package, wherein the semiconductor package defines a central axis, and comprises: a first unit, comprising: an interposer stack formed on a substrate, wherein the interposer stack comprises a plurality of interposer layers stacked together and defining a step structure on a side of the interposer stack, wherein the step structure comprises at least two step surfaces exposed from respective interposer layers; a plurality of semiconductor dice stacked adjacent to the step structure, wherein each semiconductor die is attached partially on the substrate, or on one of the step surfaces of the step structure; and an encapsulant layer formed on the substrate and encapsulating the interposer stack and the plurality of semiconductor dice; and a second unit having a structure substantially the same as that of the first unit, they are formed symmetrically with respect to the central axis, and are formed simultaneously.

[FIG. 1A]